

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: Michael S. Leung	Confirmation No. 8955
Serial No.: 10/666,399	Examiner: Abul Kalam
Filed: September 18, 2003	Art Unit: 2814
Docket No. P0298US-7	Customer No. 23935

Title: MOLDED CHIP FABRICATION METHOD AND APPARATUS

MAIL STOP AMENDMENT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**REPLY TO OFFICE ACTION**

Sir:

In response to the Office Action mailed on May 11, 2010, please enter the amendments and consider the remarks and arguments presented herein.

**AMENDMENTS TO THE CLAIMS** are reflected in the Listing of the Claims which begins on page 2 of this paper.

**REMARKS** begin on page 12 of this paper.